

App. No. 10/506,826  
Office Action Dated June 29, 2005

**Amendments to the Claims:**

This listing of claims will replace all prior versions and listing of claims in the application.

Claims 1 and 5 are amended.

Claims 8-11 are canceled.

**Listing of Claims:**

1. (Currently Amended) A semiconductor device comprising: an insulating substrate having an obverse surface formed with a ~~rectangular~~ die pad made of a metal film and a pair of electrode terminals made of a metal film; a ~~rectangular~~ semiconductor chip bonded to an obverse surface of the die pad with a die bonding material; and a molded portion made of a synthetic resin for packaging the semiconductor chip;

wherein a narrow patterned conductor made of a metal film is provided between the die pad and one of the electrode terminals to integrally connect the die pad and the electrode terminal to each other, the ~~rectangular~~ of the die pad having a length and a width which are 0.50 to 1.50 times a length and a width of the ~~rectangle~~ of the semiconductor chip, respectively;

wherein the semiconductor chip comprises an LED chip, the molded portion being light-permeable; and

wherein the die pad, the pair of electrode terminals and the narrow patterned conductor in combination provide an overall conductor pattern that is asymmetrical with respect to a longitudinal centerline of the insulating substrate, the narrow patterned conductor extending obliquely and being offset from the longitudinal centerline of the insulating substrate.

2. (Original) The semiconductor device according to claim 1, wherein the die pad has a side surface integrally formed with a narrow extension projecting outward from the die pad.

3. (Original) The semiconductor device according to claim 1, wherein the die pad is formed with a recess of a size insufficient to receive the semiconductor chip.

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4. (Original) The semiconductor device according to claim 1, wherein the die pad has a side surface integrally formed with a narrow extension projecting outward from the die pad, and wherein the die pad is formed with a recess of a size insufficient to receive the semiconductor chip.
5. (Currently Amended) A semiconductor device comprising:  
an insulating substrate having an obverse surface formed with a die pad made of a metal film and a pair of electrode terminals made of a metal film;  
a semiconductor chip which is square or generally square as viewed in plan and bonded to an obverse surface of the die pad with a die bonding material; and  
a molded portion made of a synthetic resin for packaging the semiconductor chip[[:]],  
wherein the die pad is circular as viewed in plan and has a diameter which approximates a diagonal dimension of the semiconductor chip, and  
wherein a narrow patterned conductor made of a metal film is provided between the die pad and one of the electrode terminals to integrally connect the die pad and the electrode terminal to each other, the narrow patterned conductor being positioned on a longitudinal centerline of the insulating substrate, and  
wherein the semiconductor chip has a diagonal line located on the longitudinal centerline of the insulating substrate.
6. (Original) The semiconductor device according to claim 5, wherein the diameter of the die pad is 0.6 to 1.5 times the diagonal dimension of the semiconductor chip.
7. (Previously Presented) The semiconductor device according to claim 5, wherein the semiconductor chip comprises an LED chip, and wherein the molded portion is light-permeable.
- 8-12. (Canceled)